

Windows Embedded CE 6.0 BSP for the OMAP-L13x/AM17x/AM18x

Version 1.00.01

Release Notes



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1. Introduction

This document contains the Release Notes for the Windows Embedded CE 6.0 BSP for the Texas Instruments OMAP-L138, AM18x, OMAP-L137 and AM17X processors. This is the version 1.00.01 release of the BSP.

2. What's New

Release 01.00.01:

- Added support of Boot from SD card for OMAP-L138 EVM (section Feature Summary).
- Added diskman utility for creating bootable SD card to support booting from SD card.
- Added test platform information Zoom OMAP-L138 EVM baseboard (1016660 Rev A) and SOM (1015517 Rev B) (section Testing Summary)
- Known Issues: added
 - o SDOCM00070756
 - SDOCM00073692
- Resolved Issues: added
 - o SDOCM00073707
 - o SDOCM00076103
 - SDOCM00076104
 - SDOCM00076128

See corresponding sections for more details.

3. Distribution Contents

The BSP release installation file,

OMAPL13x_AM1x_BSP_WINCE_ARM9_Release_v1.00.01.exe, contains the following files:

- Doc\ AM1x_OMAPL13x_WinCE_6.0_BSP_Release_Notes.pdf
 - These release notes

- Doc\
 - AM1x_OMAPL13x_Board_Support_Package_WinCE_Software_License_Agreement.pdf
 - Software License Agreement for the BSP
- Doc\ AM1x_OMAPL13x_WinCE_6.0_BSP_Software_Manifest.pdf
 - List of components used in the BSP
- Doc\ AM1x_OMAPL13x_WinCE_6.0_BSP_User_Guide.pdf
 - User Guide containing BSP feature descriptions and technical information
- Doc\ AM18x_OMAPL138_WinCE_6.0_BSP_Quick_Start_Guide.doc.pdf
 Quick Start Guide containing installation and build instructions for OMAP-L138 AM18x
- Doc\ AM17x_OMAPL137_WinCE_6.0_BSP_Quick_Start_Guide.pdf
 Quick Start Guide containing installation and build instructions for OMAP-L137 AM17x
- Platform* , OSDesigns* BSP and OS Design source files for OMAP-L13x, AM17x and AM18x
- Demo TI_DEFAULT* pre-built binaries for OMAP-L13x, AM17x and AM18x
- TEST* Test Plans and Test Results.

4. Requirements

Hardware required:

- For OMAP-L137 or AM1707 EVM, a suitable OMAP-L137 or AM1707 EVM, available from Spectrum Digital Inc. (http://www.spectrumdigital.com/):
 - o OMAP-L137/TMS320C6747 Floating Point Starter Kit
 - o AM1707 EVM
- For OMAP-L138 or AM1808, a suitable OMAP-L138 or AM1808 Zoom development kit, available from Logic PD (http://www.logicpd.com/):
 - o Zoom OMAP-L138/AM1808 EVM Development Kit
 - o Zoom OMAP-L138/AM1808 eXperimenter Kit
- Development PC.

See the corresponding Quick Start Guide for full details of hardware and software

required.

5. Installation Instructions

The BSP release installation file will install the source code and release documents to directory C:\TI\BSP_WINCE_ARM9_01.00.01.01\ by default.

The Quick Start Guides contain full details of how to install, build and run the BSP for the respective processor..

6. Feature Summary

The User Guide contains full details of the functionality supported by the BSP. A summary of the features supported in this BSP release is as follows:

Bootloaders:

- Boot from SD card, with EBOOT and CE image saved on SD card. In previous releases, EBOOT needs to be saved in flash. (OMAP-L138 only)
- Diskman.exe utility to create bootable SD card to support booting from SD card on OMAP-L138 EVM.
- o OMAP-L138 UBL with 300MHz ARM and DSP configuration
- AM1808 UBL with 456MHz ARM configuration
- o OMAP-L137 UBL with 300MHz ARM and DSP configuration
- AM1707 UBL with 300MHz ARM configuration
- AM1707 UBL with 456MHz ARM configuration (requires rev H EVM)
- Boot from SPI Serial Flash
- o Boot from NAND Flash
- o Boot from NOR Flash (OMAP-L138/AM1808 only)
- Ethernet download of CE image
- Load of CE image from NAND Flash
- Load of CE image from SD card
- Load of CE image from NOR Flash (OMAP-L138/AM1808 only)

- o Persistent storage of EBOOT configuration in flash
- Splash screen support
- CE 6.0 OAL supporting:
 - o KITL over Ethernet
 - VMINI Ethernet support
 - Kernel debugger
 - o Performance Profiler
 - o Real Time Clock
 - Watchdog Timer
- Drivers and libraries:
 - EDMA driver
 - o I2C driver
 - SPI driver
 - LIDD support library
 - o Character LCD driver
 - Raster LCD driver
 - EMAC NDIS Ethernet driver
 - McASP support library
 - UART Serial driver
 - o USB 1.1 OHCI driver
 - USB 2.0 Host driver
 - USB 2.0 Function driver
 - USB 2.0 OTG driver
 - NAND flash driver
 - o AIC3106 Audio driver
 - SD/MMC card driver
 - PWM driver
 - Notification LED driver
 - Power Management Suspend/Resume support

o For OMAP-L138/AM1808 only:

- UPP driver
- VPIF driver
- McBSP driver
- TPS65070 Touch Screen driver

For **OMAP-L137/AM1707 only:**

TSC2004 Touch Screen driver

7. Testing Summary

The BSP has been tested using a combination of Microsoft CETK, functional test procedures and custom test utilities. The test procedure is designed to validate all of the BSP functionality detailed in the User Guide.

The BSP has been through the full system test and validation process. Details of known issues can be found in section 7 below.

The BSP has been tested with the following software and hardware revisions:

- Zoom OMAP-L138 EVM baseboard (1016660 Rev A)
- Zoom OMAP-L138 SOM (1015517 Rev B)
- Zoom OMAP-L138 SOM revision 4
- Zoom AM1808 SOM revisions A and 2
- Zoom OMAP-L138 EVM base board revision 4
- Zoom OMAP-L138 EVM UI board revisions 6 and 7
- Logic PD 4.3" WQVGA Display Kit revisions B and C
- OMAP-L137 EVM revision E
- DA830 User Interface Board revision C
- AM1707 EVM revision H
- AM1707/OMAP-L137 User Interface Board revision B
- Windows CE 6.0 R3 with monthly updates to April 2010

8. Known Issues

Latest issues list can be tracked in the TI bug database at the link below

https://cgweb.ext.ti.com/cgweb/main?command=GenerateMainFrame&service=CQ&schema=SDO-Web&contextid=SDOWP&gueryID=34371716&usemanne=readonly&password=readonly

Known issues for both **OMAP-L138/AM1808** and **OMAP-L137/AM1707** in this release:

- SDOCM00070756 USB OTG Function CETK irregular endpoint packet size test failures
- SDOCM00070924 Transcend MMC 2G card could not be detected
- SDOCM00070932 USB OHCI CETK irregular endpoint packet size test failures
- SDOCM00073257 Silverlight bubble demo screen display shifts down by half screen

Known issues for OMAP-L138/AM1808:

- SDCM00076130 eboot takes about 3 min to load and start NK from class 2
 4GB sdhc cards.
- SDCM00073692 Current BSP supports 128MB DDR only. It needs to also support 64MB DDR found by default in LogicPD eXperimenter Kit.
- SDCM00073370 USB-Forum OPT Tests: AM1808 Fails a a number of HS-A, HS-B, FS-A and FS-B tests.
- SDOCM00070925 McBSP Throughput rates higher than expected
- SDOCM00070928 NOR filesystem not currently configured
- SDOCM00070930 Networking Pass IP settings from EBOOT to CE
- SDOCM00070934 SDHC CRC errors seen with MMCmobile card at 52MHz (bus currently limited to 26MHz)
- SDOCM00070935 EBOOTNOR Does not boot with SD card in slot
- SDOCM00071083 UPP test app number of sample points too low

Known issues for **OMAP-L137/AM1707**:

- SDOCM00070888 GPIO test to get line status fails with Rev H AM1707 board while it works fine with Rev G board
- SDOCM00070931 USB OHCI On L137 configure GPIO2_4 to control USB OVC line

 SDOCM00070932 – USB OHCI - CETK irregular endpoint packet size test failures

9. Resolved Issues

Issues for both **OMAP-L138/AM1808** resolved in this release:

- SDOCM00076103 spi eboot's default boot device should be SD card device
- SDOCM00076104 OMAP-L138 BSP hard coded to pull PMIC_PWR_ON high that causes boot up problem in 1015517 REV-B SOM cards
- SDOCM00076128 Manufacturer provided MAC address is not used to automatically configure emac device during bootup
- SDOCM00067023 MMCcard is not shown up in My Device after unplug and replug in.
- SDOCM00070759 NAND DMA support in FMD is not working
- SDOCM00070760 NAND DMA support in bootloader is not working

Issues for **OMAP-L137/AM1707** resolved in this release:

- SDOCM00070509 EBOOT sometimes fails to read CE image from SDHC card
- SDOCM00070757 USB OTG Function ActiveSync connection not reestablished after suspend / resume
- SDOCM00071318 EBOOT DSP boot menu option not working

10. Support

For technical support,

 Please post to the TI e2e WinCE community forum http://e2e.ti.com/support/embedded/f/353.aspx

Forum reported issues that are reproducible on the EVM will be entered into TI bug database and can be tracked at the link below

 $\underline{mmand=GenerateMainFrame\&service=CQ\&schema=SDO-Web\&contextid=SDOWP\&queryID=34371716\&usemame=readonly\&password=readonly&password=readonl$

2. Support for this BSP release is available via the MPC Data Support Portal: http://support.mpcdata.com/ti/

Register for support via the website and follow the instructions for raising a support request.